

1. Record Nr.	UNINA9910555157103321
Titolo	Antenna-in-package technology and applications // edited by Duixian Liu, Yueping Zhang
Pubbl/distr/stampa	Hoboken, New Jersey : , : Wiley-IEEE Press, , [2020] [Piscataway, New Jersey] : , : IEEE Xplore, , [2020]
ISBN	1-119-55664-3 1-119-55667-8 1-119-55665-1
Edizione	[First edition.]
Descrizione fisica	1 online resource (518 pages)
Disciplina	621.3824
Soggetti	Microstrip antennas
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Nota di bibliografia	Includes bibliographical references and index.
Nota di contenuto	Antennas for AiP technology / Yueping Zhang -- Package technologies / Dr Ning Ye -- Electrical, mechanical, and thermal co-design / Xiaoxiong Gu and Prithish R Parida.
Sommario/riassunto	"This book starts with some historical notes about how AiP technology has evolved as we know it today. Then, the authors consider antennas and packages, thermal analysis and design, and measurement setups and methods for AiP technology. The authors show that the choice of antennas is usually given to those popular antennas that can be easily designed for the applications; the choice of packages is a trade-off among constraints such as electrical performance, thermo-mechanical reliability, compactness, manufacturability and cost; the choice of interconnects is governed by JEDEC for automatic assembly. Next, the book describes respectively low-temperature co-fired ceramic (LTCC), high-density interconnects (HDI), fan-out wafer level packaging (FOWLP) based AiP, and 3D-printing-based AiP. After that, the authors discuss in details the surface laminar circuit (SLC) based AiP designs for large-scale mm-wave phased arrays for 94-GHz imagers and 28-GHz 5G New Radios. Finally, the book touches on 3D AiP for sensor nodes, near-field wireless power transfer, and IoT applications"--

